MC74AC257, MC74ACT257

Quad 2-Input Multiplexer with 3-State Outputs

The MC74AC257/74ACT257 is a quad 2−input multiplexer with 3−state outputs. Four bits of data from two sources can be selected using a Common Data Select input. The four outputs present the selected data in true (noninverted) form. The outputs may be switched to a high impedance state by placing a logic HIGH on the common Output Enable ($\overline{OE}$) input, allowing the outputs to interface directly with bus−oriented systems.

- Multiplexer Expansion by Tying Outputs Together
- Noninverting 3−State Outputs
- Outputs Source/Sink 24 mA
- ′ACT257 Has TTL Compatible Inputs
- **These devices are available in Pb−free package(s). Specifications herein apply to both standard and Pb−free devices. Please see our website at www.onsemi.com for specific Pb−free orderable part numbers, or contact your local ON Semiconductor sales office or representative.**

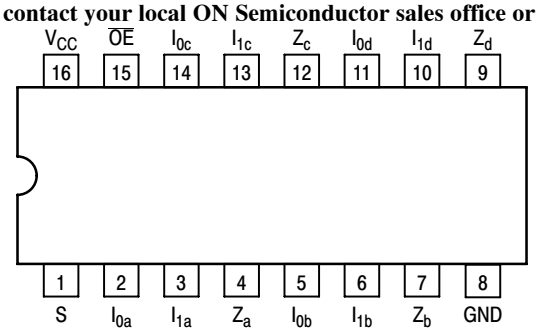

Figure 1. Pinout: 16−Lead Packages Conductors
(Top View)

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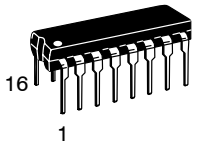
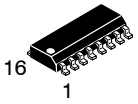
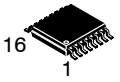


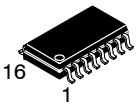
DIP−16
N SUFFIX
CASE 648



SO−16
D SUFFIX
CASE 751B



TSSOP−16
DT SUFFIX
CASE 948F



EIAJ−16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC257N	PDIP−16	25 Units/Rail
MC74ACT257N	PDIP−16	25 Units/Rail
MC74AC257D	SOIC−16	48 Units/Rail
MC74ACT257D	SOIC−16	48 Units/Rail
MC74AC257DR2	SOIC−16	2500 Tape & Reel
MC74ACT257DR2	SOIC−16	2500 Tape & Reel
MC74AC257DT	TSSOP−16	96 Units/Rail
MC74ACT257DT	TSSOP−16	96 Units/Rail
MC74AC257DTR2	TSSOP−16	2500 Tape & Reel
MC74ACT257DTR2	TSSOP−16	2500 Tape & Reel
MC74ACT257M	EIAJ−16	50 Units/Rail
MC74AC257MEL	EIAJ−16	2000 Tape & Reel
MC74ACT257MEL	EIAJ−16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 8 of this data sheet.

PIN NAME

PIN	FUNCTION
S	Common Data Select Input
$\overline{OE}$	3−State Output Enable Input
I_{0a}−I_{0d}	Data Inputs from Source 0
I_{1a}−I_{1d}	Data Inputs from Source 1
Z_a−Z_d	3−State Multiplexer Outputs

TRUTH TABLE

Output Enable	Select Input	Data Inputs		Outputs
$\overline{OE}$	S	I_0	I_1	Z
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

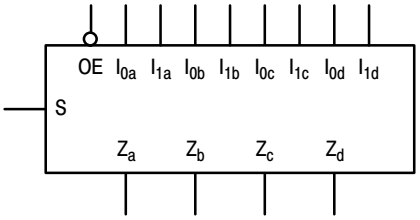


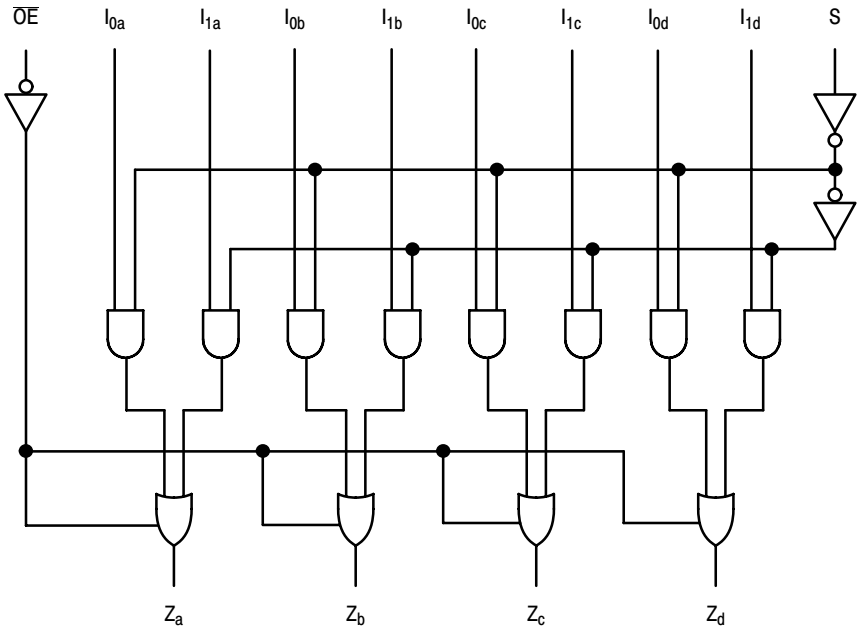
Figure 2. Logic Symbol

FUNCTIONAL DESCRIPTION

The MC74AC257/74ACT257 is a quad 2−input multiplexer with 3−state outputs. It selects four bits of data from two sources under control of a Common Data Select input. When the Select input is LOW, the I_{0x} inputs are selected and when Select is HIGH, the I_{1x} inputs are selected. The data on the selected inputs appears at the outputs in true (noninverted) form. The device is the logic implementation of a 4−pole, 2−position switch where the position of the switch is determined by the logic levels supplied to the Select input. The logic equations for the outputs are shown below:

$$Z_a = \overline{OE} \cdot (I_{1a} \cdot S + I_{0a} \cdot \overline{S})$$
$$Z_b = \overline{OE} \cdot (I_{1b} \cdot S + I_{0b} \cdot \overline{S})$$
$$Z_c = \overline{OE} \cdot (I_{1c} \cdot S + I_{0c} \cdot \overline{S})$$
$$Z_d = \overline{OE} \cdot (I_{1d} \cdot S + I_{0d} \cdot \overline{S})$$

When the Output Enable input ($\overline{OE}$) is HIGH, the outputs are forced to a high impedance state. If the outputs are tied together, all but one device must be in the high impedance state to avoid high currents that would exceed the maximum ratings. Designers should ensure the Output Enable signals to 3−state devices whose outputs are tied together are designed so there is no overlap.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	−0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	−0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	−0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	−65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		−40	25	85	°C
I_{OH}	Output Current − High		–	–	−24	mA
I_{OL}	Output Current − Low		–	–	24	mA

1. 1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. 2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC		74AC	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay I_n to Z_n	3.3 5.0	1.5 1.5	5.0 4.0	8.5 6.0	1.0 1.0	9.0 7.0	ns	3–5
t_{PHL}	Propagation Delay I_n to Z_n	3.3 5.0	1.5 1.5	6.0 4.5	8.5 6.0	1.0 1.0	9.0 7.0	ns	3–5
t_{PLH}	Propagation Delay S to Z_n	3.3 5.0	1.5 1.5	7.0 5.0	10.5 7.5	1.5 1.0	11.5 8.5	ns	3–6
t_{PHL}	Propagation Delay S to Z_n	3.3 5.0	1.5 1.5	7.5 5.5	10.5 7.5	1.5 1.0	11.5 8.5	ns	3–6
t_{PZH}	Output Enable Time	3.3 5.0	1.5 1.5	6.5 5.0	9.5 7.5	1.0 1.0	10.5 8.5	ns	3–7
t_{PZL}	Output Enable Time	3.3 5.0	1.5 1.5	5.5 5.0	9.0 8.5	1.0 1.0	10.0 9.5	ns	3–8
t_{PHZ}	Output Disable Time	3.3 5.0	1.5 1.5	5.5 5.0	10.0 9.0	1.0 1.0	11.0 10.0	ns	3–7
t_{PLZ}	Output Disable Time	3.3 5.0	1.5 1.5	5.5 5.0	9.0 8.0	1.0 1.0	10.0 9.0	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay I_n to Z_n	5.0	1.5	5.0	7.0	1.0	7.5	ns	3–6
t_{PHL}	Propagation Delay I_n to Z_n	5.0	2.0	6.0	7.5	1.5	8.5	ns	3–6
t_{PLH}	Propagation Delay S to Z_n	5.0	2.0	7.0	9.5	1.5	10.5	ns	3–6
t_{PHL}	Propagation Delay S to Z_n	5.0	2.5	7.0	10.5	2.0	11.5	ns	3–6
t_{PZH}	Output Enable Time	5.0	2.0	6.0	8.0	1.5	9.0	ns	3–7
t_{PZL}	Output Enable Time	5.0	2.0	6.0	8.0	1.5	9.0	ns	3–8
t_{PHZ}	Output Disable Time	5.0	2.5	6.5	9.0	1.5	10.0	ns	3–7
t_{PLZ}	Output Disable Time	5.0	2.0	6.0	7.5	1.5	8.5	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

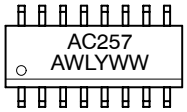
CAPACITANCE

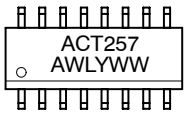
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	50	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

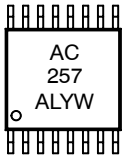
DIP–16

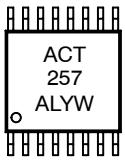
SO–16



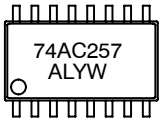


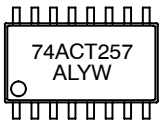
TSSOP–16





EIAJ–16

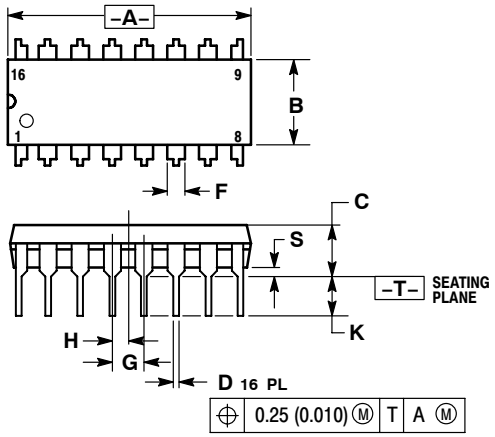




A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

PACKAGE DIMENSIONS

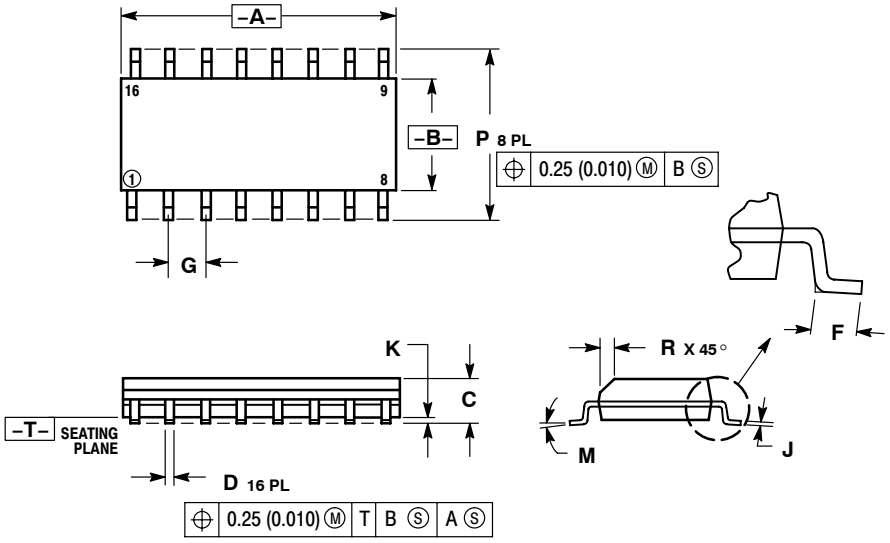
PDIP–16
N SUFFIX
16 PIN PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

SO–16
D SUFFIX
16 PIN PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J

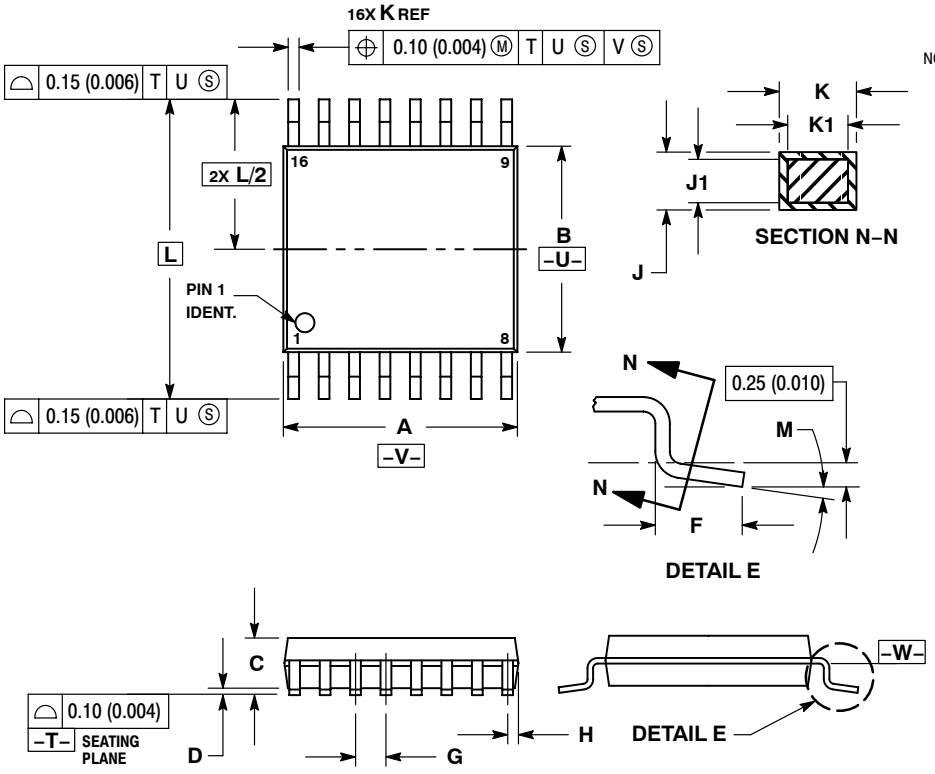


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

TSSOP−16
DT SUFFIX
16 PIN PLASTIC TSSOP PACKAGE
CASE948F−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

EIAJ−16
M SUFFIX
16 PIN PLASTIC EIAJ PACKAGE
CASE966−01
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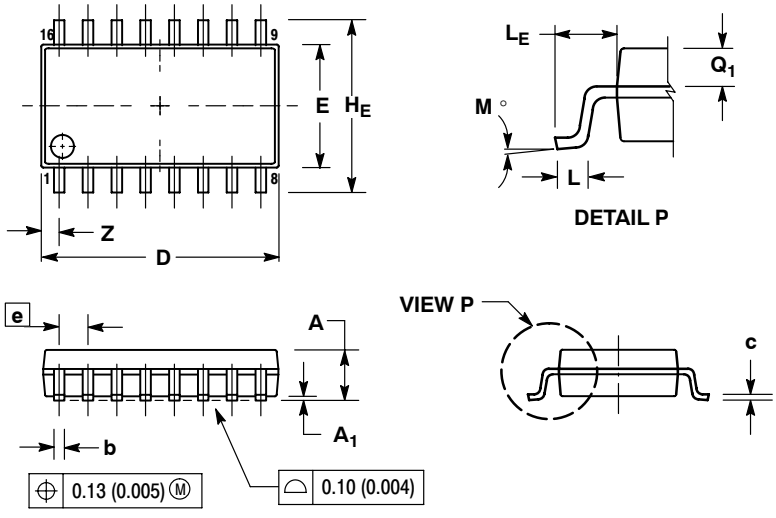

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

Notes

Notes

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